

MURHB840CTG, MURHB840CTT4G, SURHB8840CTT4G

Power Rectifier D²PAK Power Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Package Designed for Power Surface Mount Applications
- Ultrafast 28 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- High Temperature Glass Passivated Junction
- High Voltage Capability
- Low Leakage Specified @ 150°C Case Temperature
- Short Heat Sink Tab Manufactured – Not Sheared!
- Similar in Size to Industrial Standard TO-220 Package
- SURHB8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- SURHB8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Packages are Pb-Free*

Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL 94, V-0
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings:
 - ♦ Machine Model, C (> 400 V)
 - ♦ Human Body Model, 3B (> 8000 V)

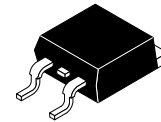
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



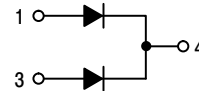
ON Semiconductor®

<http://onsemi.com>

ULTRAFAST RECTIFIER 8.0 AMPERES, 400 VOLTS



**D²PAK
CASE 418B
STYLE 3**



MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
UH840 = Device Code
G = Pb-Free Package
AKA = Diode Polarity

ORDERING INFORMATION

| Device | Package | Shipping† |
|----------------|---------------------------------|----------------------|
| MURHB840CTG | D ² PAK (Pb-Free) | 50 Units/Rail |
| MURHB840CTT4G | D ² PAK (Pb-Free) | 800 / Tape & Reel |
| SURHB8840CTT4G | D ² PAK (Pb-Free) | 800 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MURHB840CTG, MURHB840CTT4G, SURHB8840CTT4G

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---------------------------------|-------------|------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 400 | V |
| Average Rectified Forward Current (Rated V_R , $T_C = 120^\circ\text{C}$) Total Device | $I_{F(AV)}$ | 4.0 8.0 | A |
| Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, $T_C = 120^\circ\text{C}$) | I_{FM} | 8.0 | A |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I_{FSM} | 100 | A |
| Controlled Avalanche Energy | W_{AVAIL} | 20 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -65 to +175 | $^\circ\text{C}$ |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS (Per Leg)

| Rating | Symbol | Value | Unit |
|---|-----------------|-------|---------------------------|
| Maximum Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 3.0 | $^\circ\text{C}/\text{W}$ |
| Maximum Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 50 | $^\circ\text{C}/\text{W}$ |

ELECTRICAL CHARACTERISTICS (Per Leg)

| Characteristic | Symbol | Value | Unit |
|---|----------|------------|---------------|
| Maximum Instantaneous Forward Voltage (Note 1) ($i_F = 4.0\text{ A}$, $T_C = 150^\circ\text{C}$) ($i_F = 4.0\text{ A}$, $T_C = 25^\circ\text{C}$) | V_F | 1.9 2.2 | V |
| Maximum Instantaneous Reverse Current (Note 1) (Rated DC Voltage, $T_C = 150^\circ\text{C}$) (Rated DC Voltage, $T_C = 25^\circ\text{C}$) | i_R | 500 10 | μA |
| Maximum Reverse Recovery Time ($I_F = 1.0\text{ A}$, $di/dt = 50\text{ A}/\mu\text{s}$) | t_{rr} | 28 | ns |
| Typical Peak Reverse Recovery Current ($I_F = 1.0\text{ A}$, $di/dt = 50\text{ A}/\mu\text{s}$) | I_{RM} | 0.7 | A |

1. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$

MURHB840CTG, MURHB840CTT4G, SURHB8840CTT4G

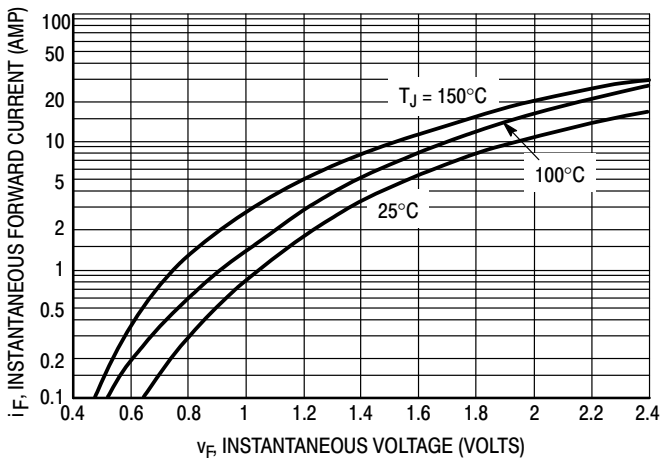


Figure 1. Typical Forward Voltage

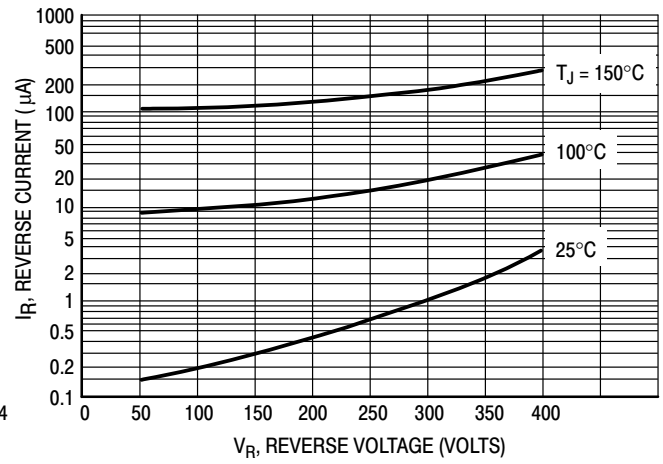


Figure 2. Typical Reverse Current, Per Leg

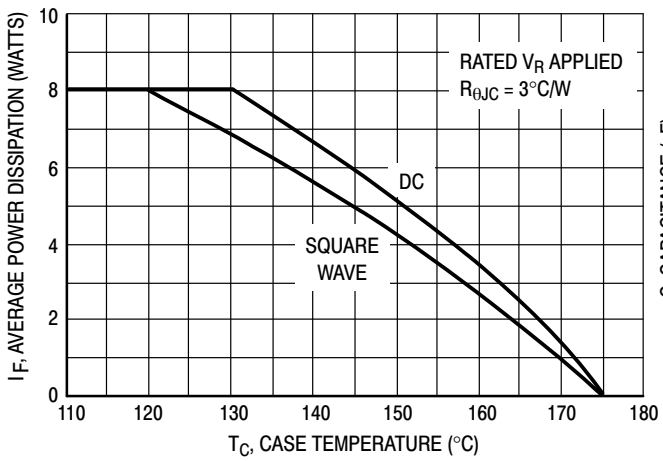


Figure 3. Current Derating, Case

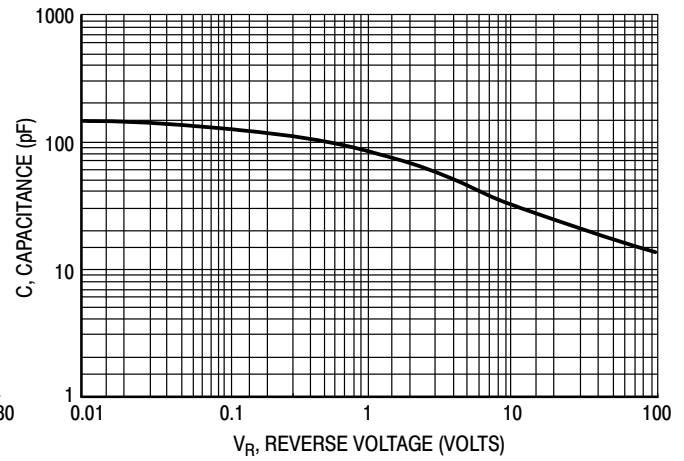


Figure 4. Typical Capacitance, Per Leg

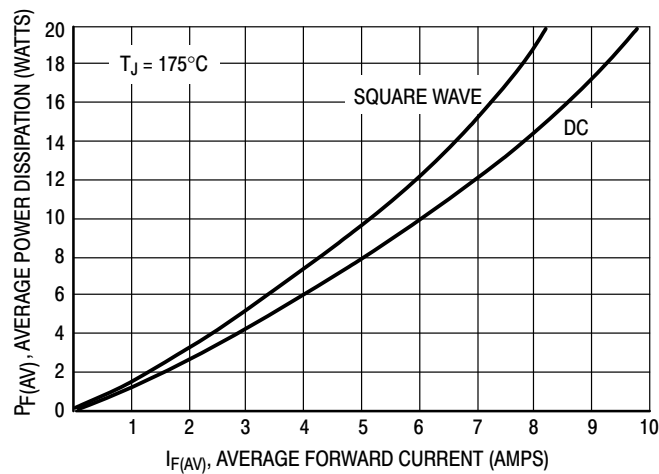


Figure 5. Forward Power Dissipation, Per Leg

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

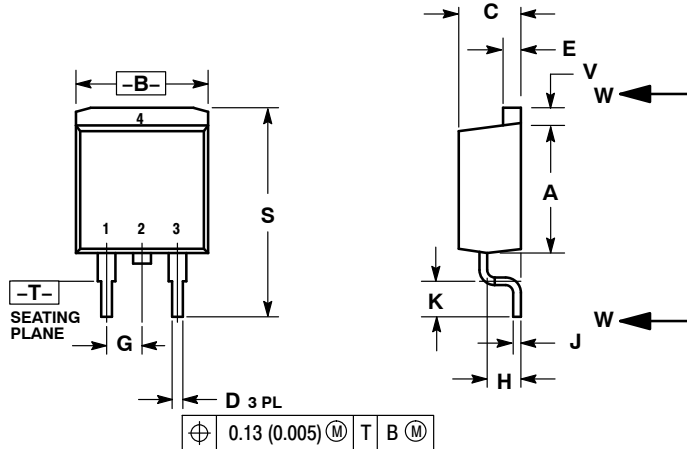
ON Semiconductor®



D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

SCALE 1:1

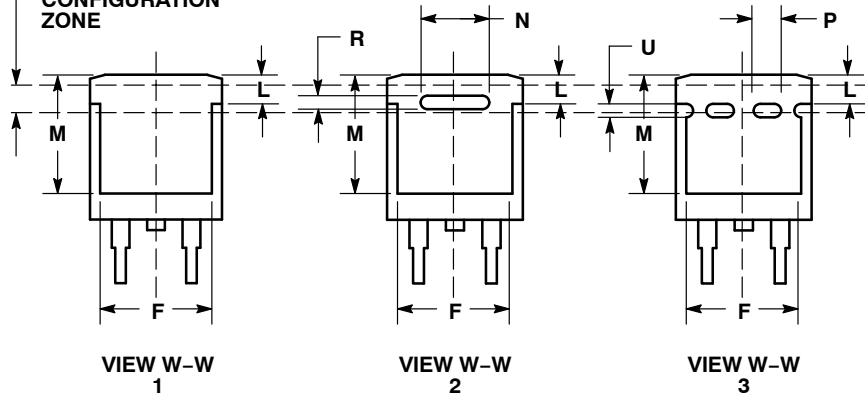


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.340 | 0.380 | 8.64 | 9.65 |
| B | 0.380 | 0.405 | 9.65 | 10.29 |
| C | 0.160 | 0.190 | 4.06 | 4.83 |
| D | 0.020 | 0.035 | 0.51 | 0.89 |
| E | 0.045 | 0.055 | 1.14 | 1.40 |
| F | 0.310 | 0.350 | 7.87 | 8.89 |
| G | 0.100 | BSC | 2.54 | BSC |
| H | 0.080 | 0.110 | 2.03 | 2.79 |
| J | 0.018 | 0.025 | 0.46 | 0.64 |
| K | 0.090 | 0.110 | 2.29 | 2.79 |
| L | 0.052 | 0.072 | 1.32 | 1.83 |
| M | 0.280 | 0.320 | 7.11 | 8.13 |
| N | 0.197 | REF | 5.00 | REF |
| P | 0.079 | REF | 2.00 | REF |
| R | 0.039 | REF | 0.99 | REF |
| S | 0.575 | 0.625 | 14.60 | 15.88 |
| V | 0.045 | 0.055 | 1.14 | 1.40 |

VARIABLE CONFIGURATION ZONE



- | | | | | | |
|--|---|---|--|---|--|
| STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR | STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN | STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE | STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR | STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE | STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE 4. CATHODE |
|--|---|---|--|---|--|

MARKING INFORMATION AND FOOTPRINT ON PAGE 2

| | | |
|-------------------------|---------------------------|--|
| DOCUMENT NUMBER: | 98ASB42761B | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION: | D²PAK 3 | PAGE 1 OF 2 |

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

**GENERIC
MARKING DIAGRAM***



- xx = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package
- AKA = Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|-------------------------|---------------------------|--|
| DOCUMENT NUMBER: | 98ASB42761B | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION: | D²PAK 3 | PAGE 2 OF 2 |

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales